SOT1780-8

WLCSP36, wafer level chip-scale package, 36 terminals, 0.4 mm pitch, 3.9 mm x 1.9 mm x 0.525 mm body (backside coating included)

11 July 2018 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	20-06-2018
Manufacturer package code	98ASA01264D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3.9	-	mm
package width	-	1.9	-	mm
package height	-	0.525	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	

2 Package outline

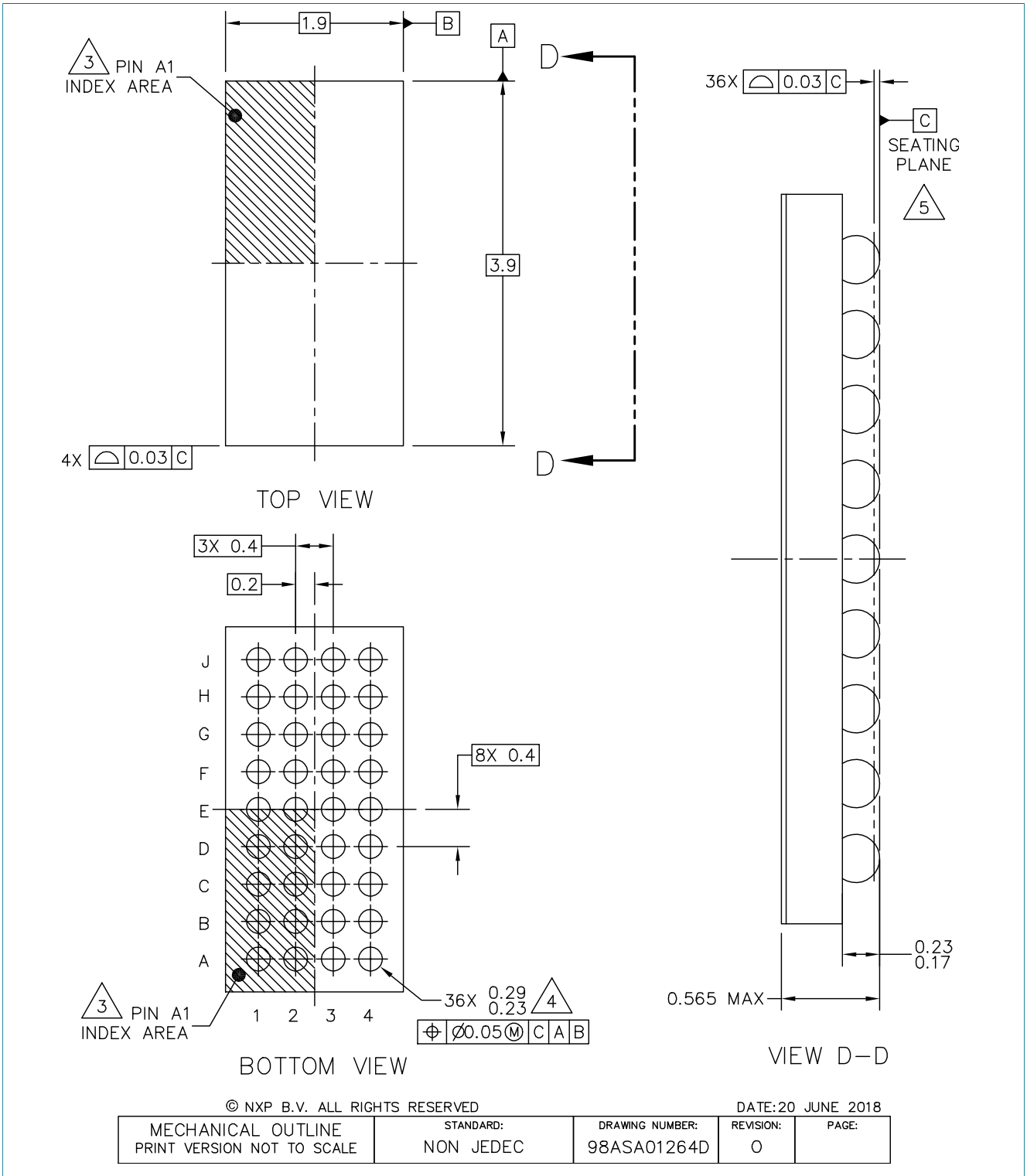

Figure 1. Package outline WLCSP36 (SOT1780-8)

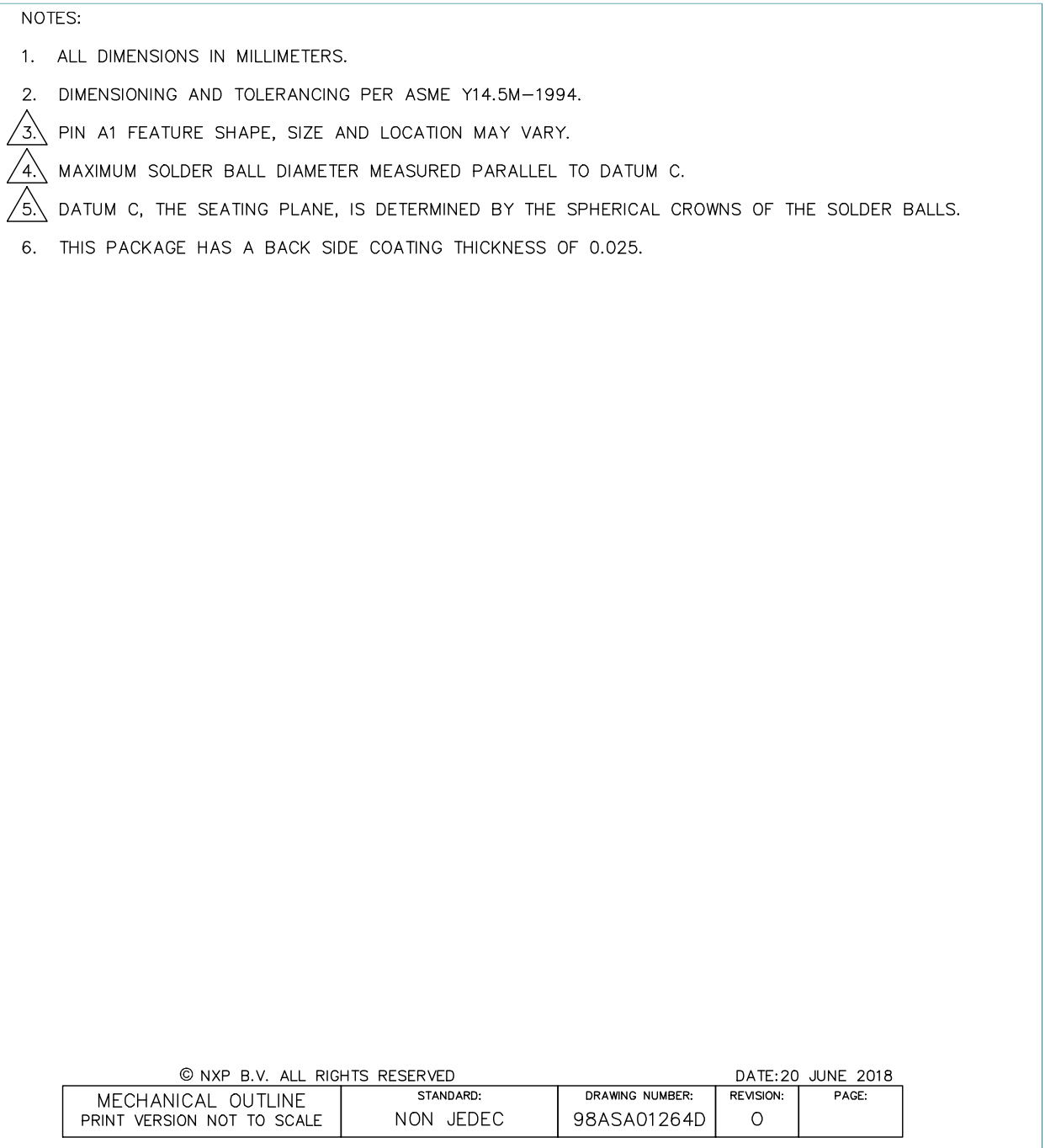

Figure 2. Package outline note WLCSP36 (SOT1780-8)

3 Soldering

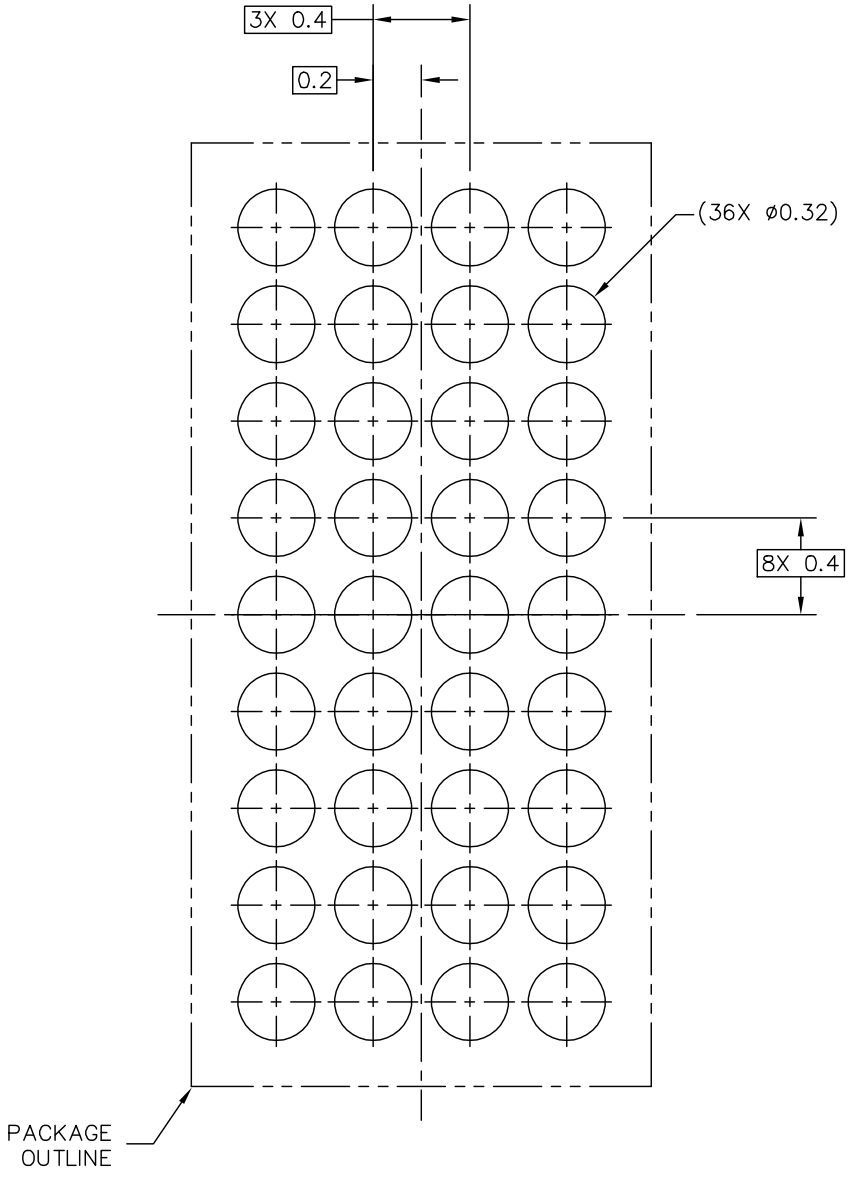

Figure 3. Reflow soldering footprint part1 for WLCSP36 (SOT1780-8)

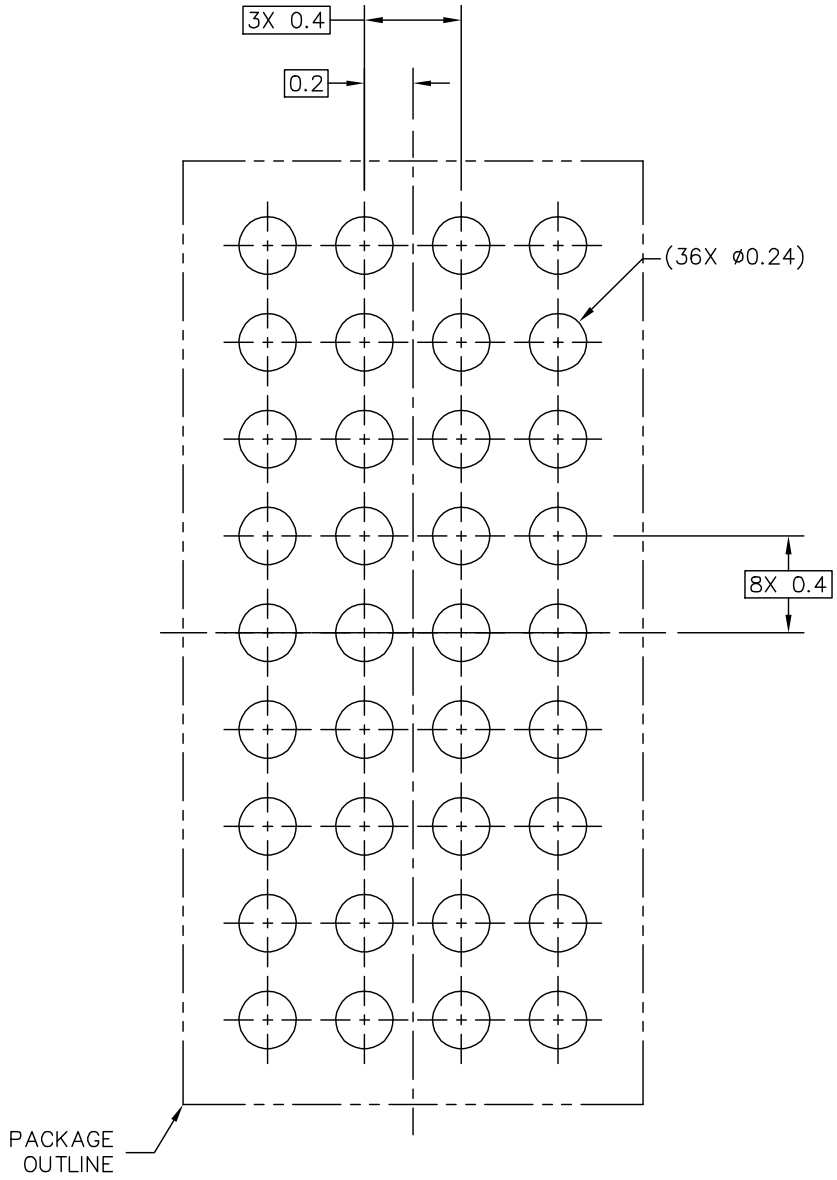

Figure 4. Reflow soldering footprint part2 for WLCSP36 (SOT1780-8)

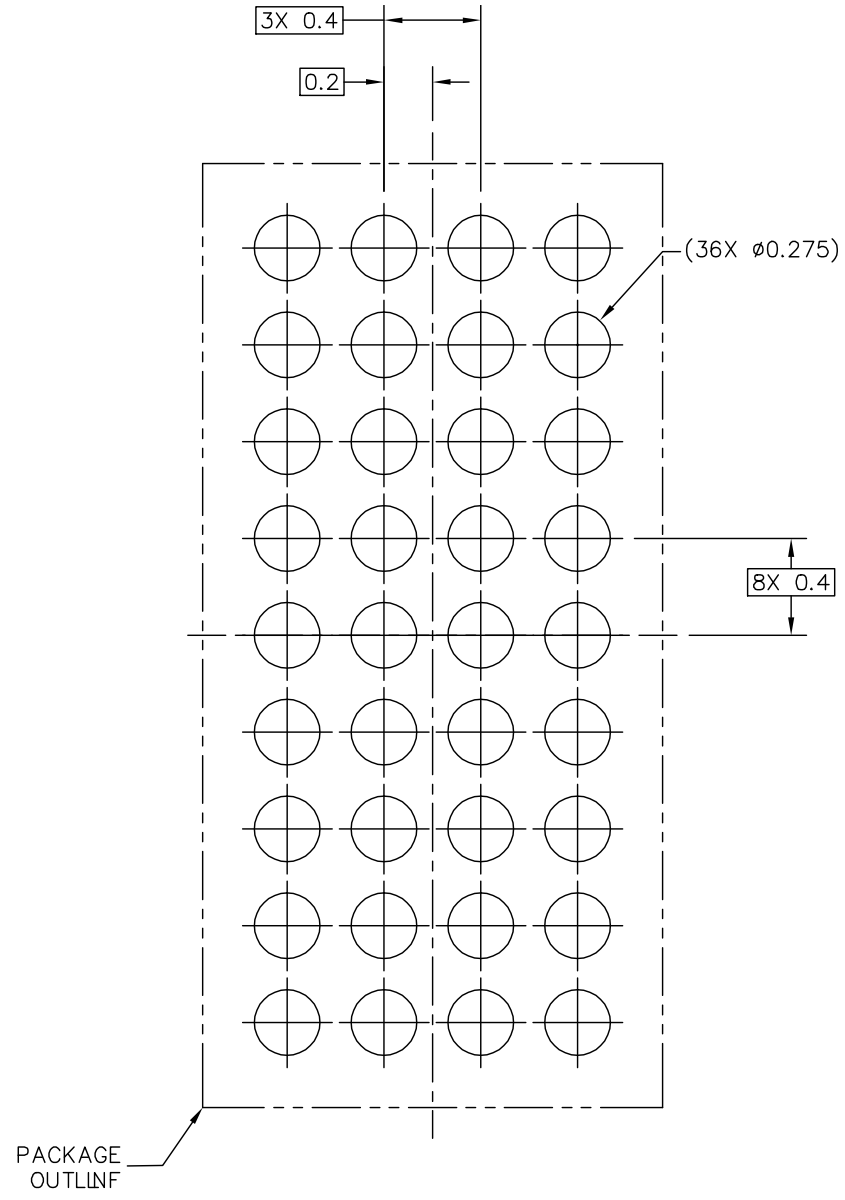

Figure 5. Reflow soldering footprint part3 for WLCSP36 (SOT1780-8)

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For more information, please visit: http://www.nxp.com
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